

MOSFET

OptiMOS™FD Power-Transistor, 250 V

Features

- N-channel, normal level
- Excellent gate charge x $R_{DS(on)}$ product (FOM)
- Very low on-resistance $R_{DS(on)}$
- Pb-free lead plating; RoHS compliant
- Halogen-free according to IEC61249-2-21
- Ideal for high-frequency switching and synchronous rectification
- 175°C rated

Product Validation:

Qualified for industrial applications according to the relevant tests of JEDEC47/20/22

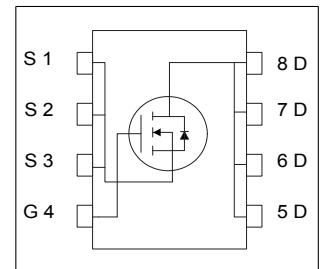


Table 1 Key Performance Parameters

Parameter	Value	Unit
V_{DS}	250	V
$R_{DS(on),max}$	43	mΩ
I_D	36	A

Type / Ordering Code	Package	Marking	Related Links
BSC430N25NSFD	TSON-8-3	430N25F	-

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1 Maximum ratings

at $T_A=25\text{ °C}$, unless otherwise specified

Table 2 Maximum ratings

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current	I_D	-	-	36 26	A	$T_C=25\text{ °C}$ $T_C=100\text{ °C}$
Pulsed drain current ¹⁾	$I_{D,pulse}$	-	-	144	A	$T_C=25\text{ °C}$
Avalanche energy, single pulse	E_{AS}	-	-	159	mJ	$I_D=23\text{ A}$, $R_{GS}=25\ \Omega$
Reverse diode dv/dt	dv/dt	-	-	60	kV/ μ s	$I_D=36\text{ A}$, $V_{DS}=125\text{ V}$, $di/dt=1500\text{ A}/\mu\text{s}$, $T_{j,max}=175\text{ °C}$
Gate source voltage	V_{GS}	-20	-	20	V	-
Power dissipation	P_{tot}	-	-	214	W	$T_C=25\text{ °C}$
Operating and storage temperature	T_j , T_{stg}	-55	-	175	°C	IEC climatic category; DIN IEC 68-1: 55/175/56

2 Thermal characteristics

at $T_j=25\text{ °C}$, unless otherwise specified

Table 3 Thermal characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	R_{thJC}	-	0.4	0.7	K/W	-
Thermal resistance, junction - ambient, minimal footprint	R_{thJA}	-	-	75	K/W	-
Thermal resistance, junction - ambient, 6 cm ² cooling area ²⁾	R_{thJA}	-	-	50	K/W	-

¹⁾ See Diagram 3

²⁾ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 μ m thick) copper area for drain connection. PCB is vertical in still air.

3 Electrical characteristics

at $T_j=25\text{ °C}$, unless otherwise specified

Table 4 Static characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	250	-	-	V	$V_{GS}=0\text{ V}$, $I_D=1\text{ mA}$
Gate threshold voltage	$V_{GS(th)}$	2	3	4	V	$V_{DS}=V_{GS}$, $I_D=137\text{ }\mu\text{A}$
Zero gate voltage drain current	I_{DSS}	-	0.1 10	1 100	μA	$V_{DS}=200\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=25\text{ °C}$ $V_{DS}=200\text{ V}$, $V_{GS}=0\text{ V}$, $T_j=125\text{ °C}$
Gate-source leakage current	I_{GSS}	-	1	100	nA	$V_{GS}=20\text{ V}$, $V_{DS}=0\text{ V}$
Drain-source on-state resistance	$R_{DS(on)}$	-	34	43	m Ω	$V_{GS}=10\text{ V}$, $I_D=36\text{ A}$
Gate resistance ¹⁾	R_G	-	3.6	5.4	Ω	-
Transconductance	g_{fs}	37	73	-	S	$ V_{DS} >2 I_D R_{DS(on)max}$, $I_D=36\text{ A}$

Table 5 Dynamic characteristics

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance ¹⁾	C_{iss}	-	2770	3680	pF	$V_{GS}=0\text{ V}$, $V_{DS}=125\text{ V}$, $f=1\text{ MHz}$
Output capacitance ¹⁾	C_{oss}	-	157	209	pF	$V_{GS}=0\text{ V}$, $V_{DS}=125\text{ V}$, $f=1\text{ MHz}$
Reverse transfer capacitance ¹⁾	C_{rss}	-	6	10	pF	$V_{GS}=0\text{ V}$, $V_{DS}=125\text{ V}$, $f=1\text{ MHz}$
Turn-on delay time	$t_{d(on)}$	-	8	-	ns	$V_{DD}=125\text{ V}$, $V_{GS}=10\text{ V}$, $I_D=16.5\text{ A}$, $R_{G,ext}=1.6\text{ }\Omega$
Rise time	t_r	-	6	-	ns	$V_{DD}=125\text{ V}$, $V_{GS}=10\text{ V}$, $I_D=16.5\text{ A}$, $R_{G,ext}=1.6\text{ }\Omega$
Turn-off delay time	$t_{d(off)}$	-	29	-	ns	$V_{DD}=125\text{ V}$, $V_{GS}=10\text{ V}$, $I_D=16.5\text{ A}$, $R_{G,ext}=1.6\text{ }\Omega$
Fall time	t_f	-	10	-	ns	$V_{DD}=125\text{ V}$, $V_{GS}=10\text{ V}$, $I_D=16.5\text{ A}$, $R_{G,ext}=1.6\text{ }\Omega$

Table 6 Gate charge characteristics²⁾

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	Q_{gs}	-	13	-	nC	$V_{DD}=125\text{ V}$, $I_D=36\text{ A}$, $V_{GS}=0\text{ to }10\text{ V}$
Gate to drain charge ¹⁾	Q_{gd}	-	4.1	-	nC	$V_{DD}=125\text{ V}$, $I_D=36\text{ A}$, $V_{GS}=0\text{ to }10\text{ V}$
Switching charge	Q_{sw}	-	8.3	-	nC	$V_{DD}=125\text{ V}$, $I_D=36\text{ A}$, $V_{GS}=0\text{ to }10\text{ V}$
Gate charge total ¹⁾	Q_g	-	34	42	nC	$V_{DD}=125\text{ V}$, $I_D=36\text{ A}$, $V_{GS}=0\text{ to }10\text{ V}$
Gate plateau voltage	$V_{plateau}$	-	4.5	-	V	$V_{DD}=125\text{ V}$, $I_D=36\text{ A}$, $V_{GS}=0\text{ to }10\text{ V}$
Output charge ¹⁾	Q_{oss}	-	74	99	nC	$V_{DD}=125\text{ V}$, $V_{GS}=0\text{ V}$

¹⁾ Defined by design. Not subject to production test

²⁾ See "Gate charge waveforms" for parameter definition

Table 7 Reverse diode

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode continuous forward current	I_S	-	-	36	A	$T_C=25\text{ °C}$
Diode pulse current ¹⁾	$I_{S,pulse}$	-	-	144	A	$T_C=25\text{ °C}$
Diode hard commutation current ²⁾	$I_{S,hard}$	-	-	36	A	$T_C=25\text{ °C}$, $di/dt=1500\text{ A}/\mu\text{s}$
Diode forward voltage	V_{SD}	-	0.9	1.2	V	$V_{GS}=0\text{ V}$, $I_F=36\text{ A}$, $T_J=25\text{ °C}$
Reverse recovery time ³⁾	t_{rr}	-	96	-	ns	$V_R=125\text{ V}$, $I_F=12.5\text{ A}$, $di_F/dt=100\text{ A}/\mu\text{s}$
Reverse recovery charge ³⁾	Q_{rr}	-	227	-	nC	$V_R=125\text{ V}$, $I_F=12.5\text{ A}$, $di_F/dt=100\text{ A}/\mu\text{s}$

¹⁾ Diode pulse current is defined by thermal and/or package limits

²⁾ Maximum allowed hard-commutated current through diode at $di/dt=1500\text{ A}/\mu\text{s}$

³⁾ Defined by design. Not subject to production test

4 Electrical characteristics diagrams

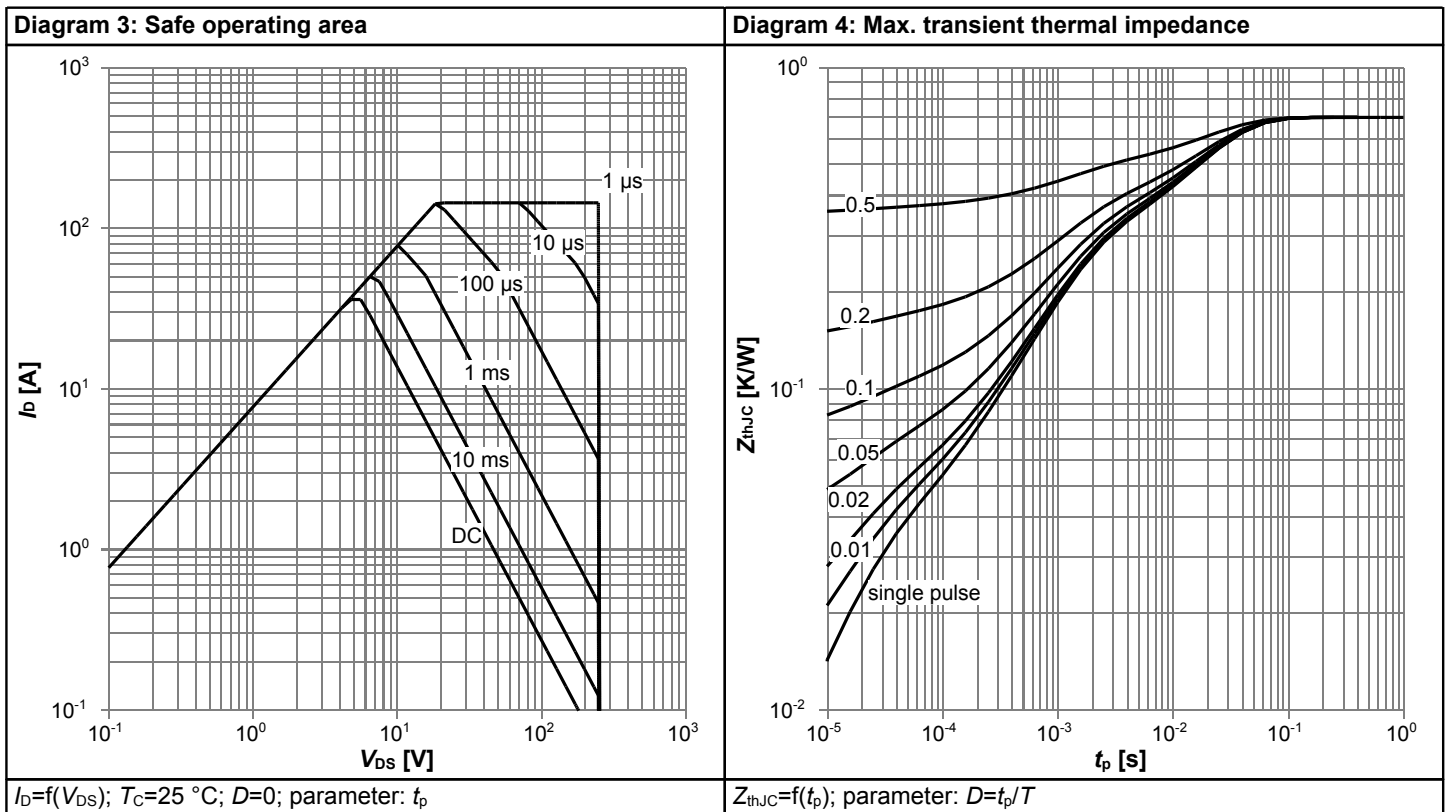
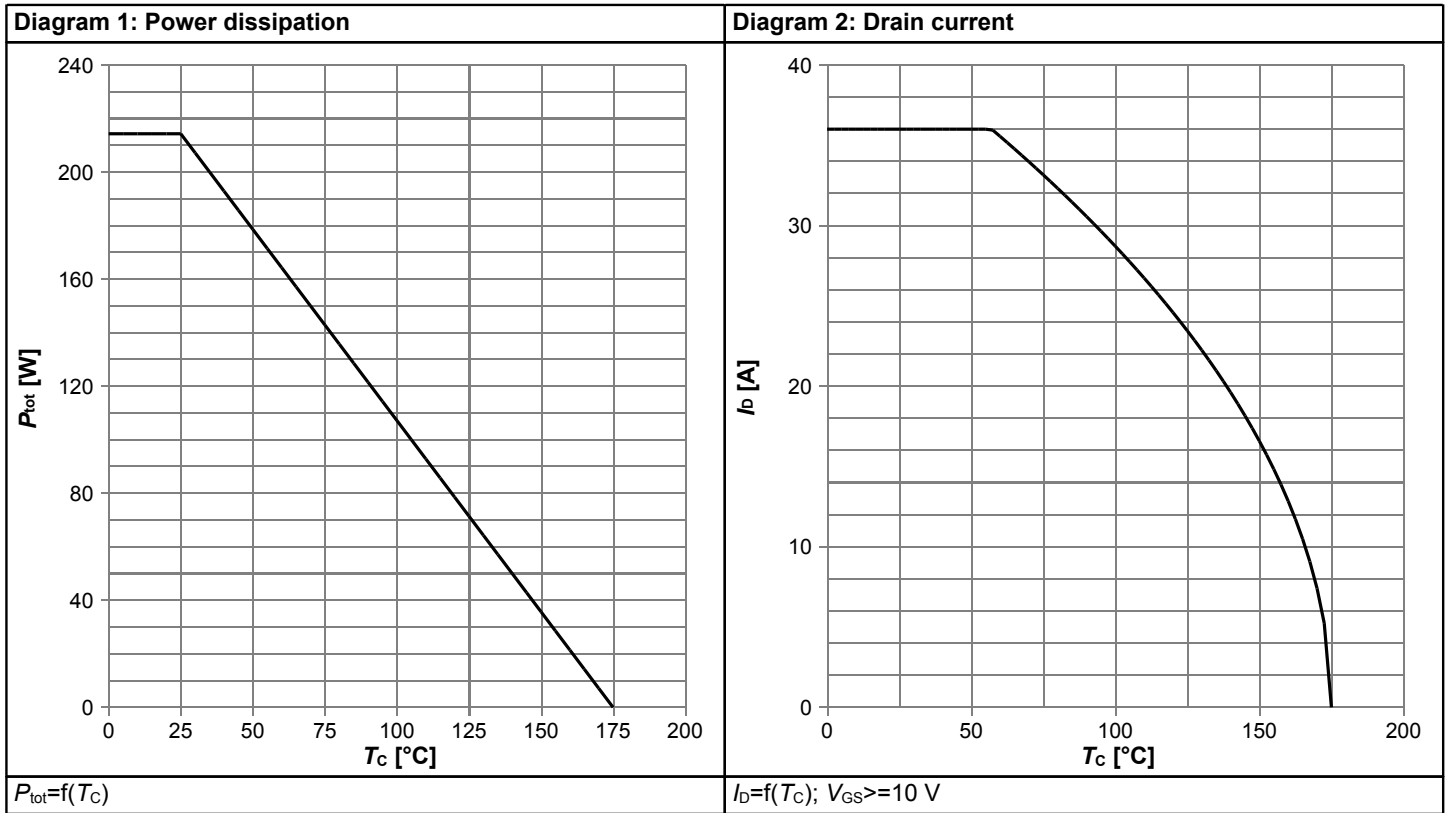
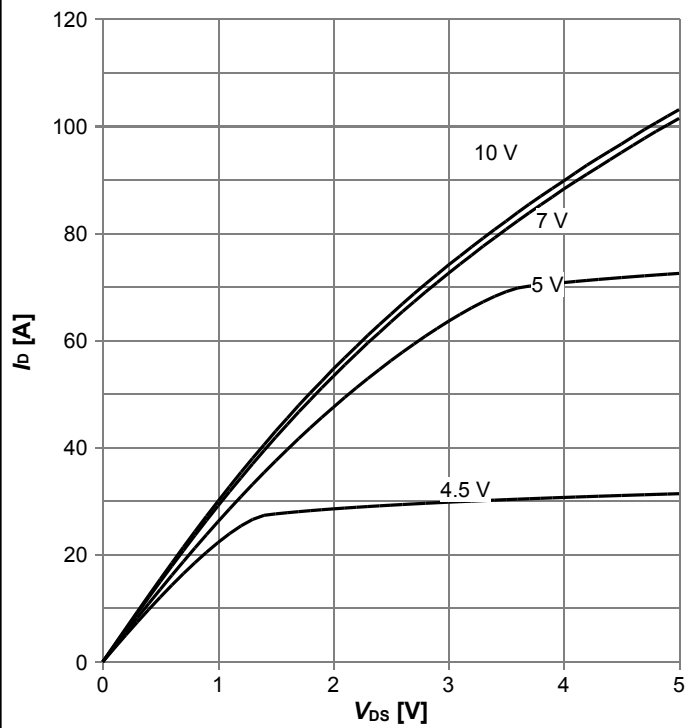
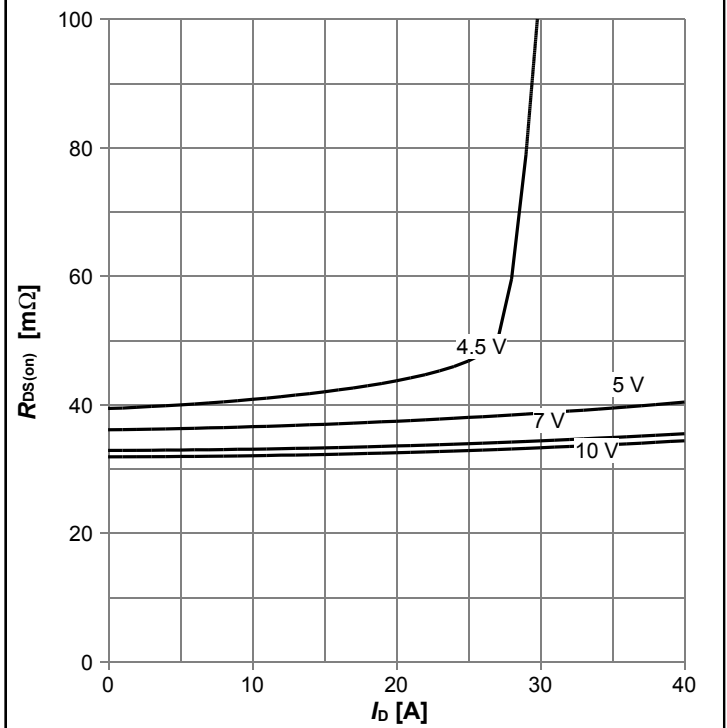


Diagram 5: Typ. output characteristics



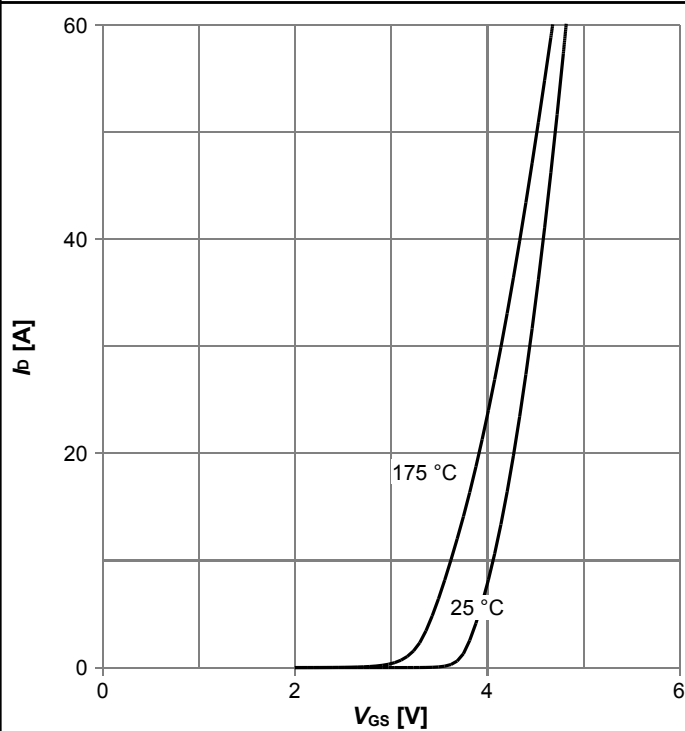
$I_D=f(V_{DS}); T_j=25\text{ }^\circ\text{C};$ parameter: V_{GS}

Diagram 6: Typ. drain-source on resistance



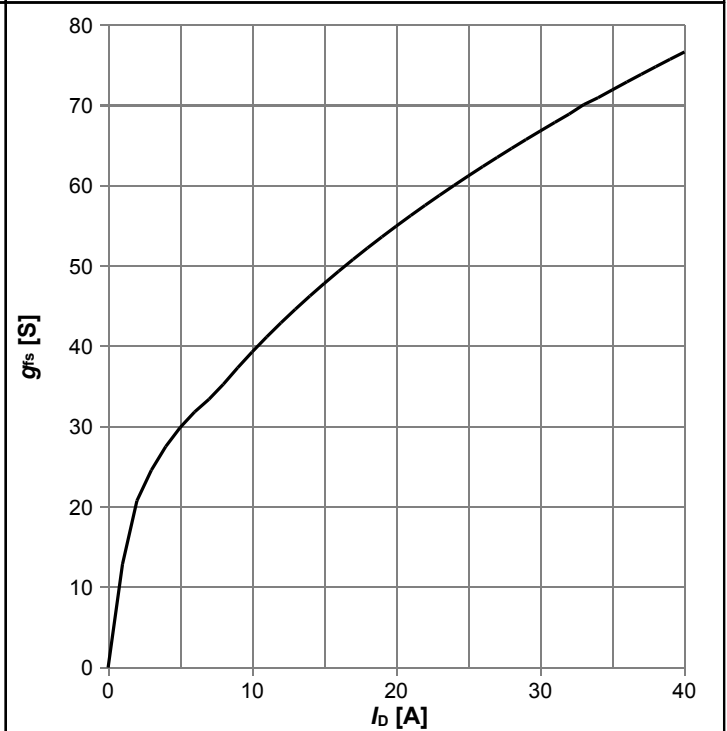
$R_{DS(on)}=f(I_D); T_j=25\text{ }^\circ\text{C};$ parameter: V_{GS}

Diagram 7: Typ. transfer characteristics



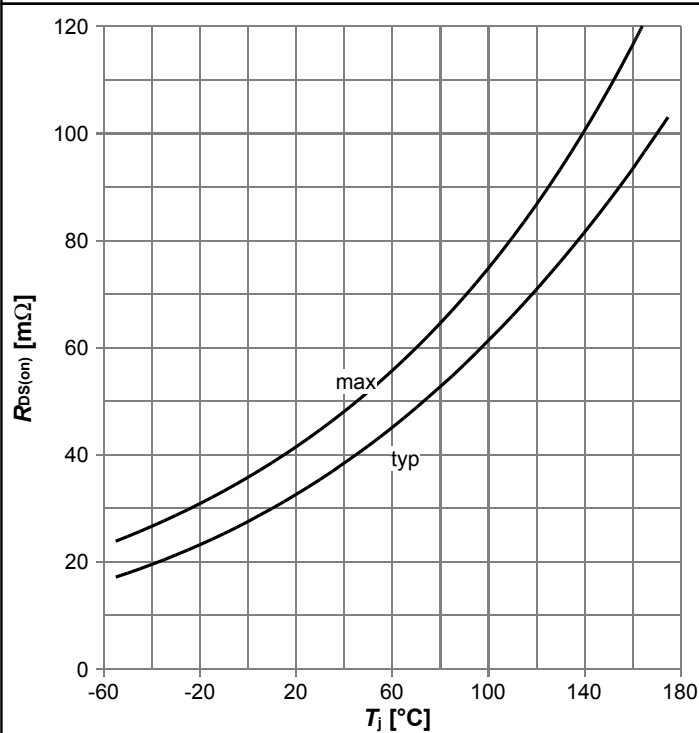
$I_D=f(V_{GS}); |V_{DS}|>2I_D R_{DS(on)max};$ parameter: T_j

Diagram 8: Typ. forward transconductance



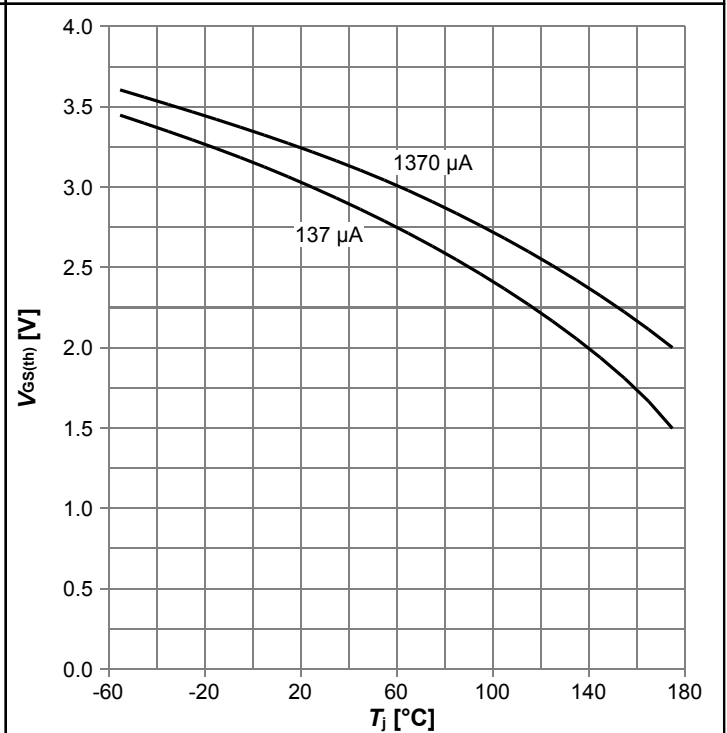
$g_{fs}=f(I_D); T_j=25\text{ }^\circ\text{C}$

Diagram 9: Drain-source on-state resistance



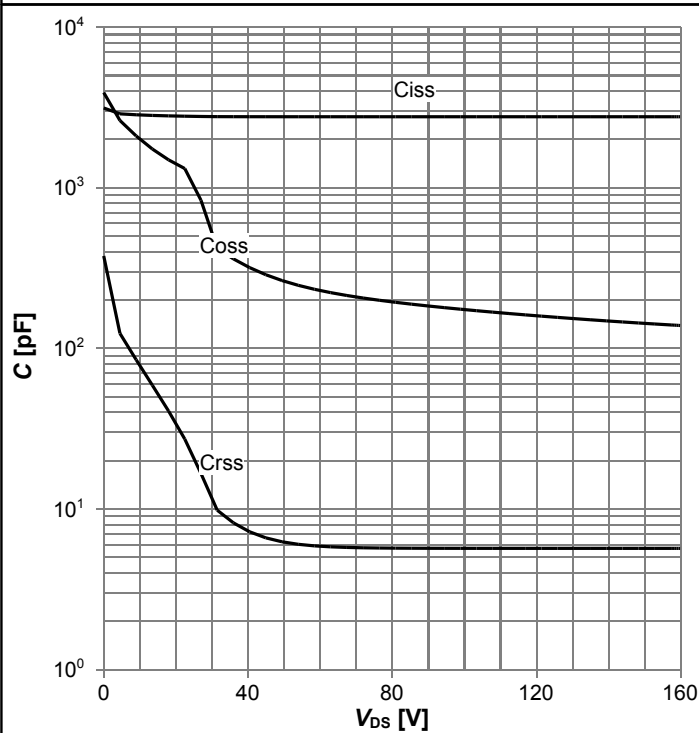
$R_{DS(on)}=f(T_j)$; $I_D=37\text{ A}$; $V_{GS}=10\text{ V}$

Diagram 10: Typ. gate threshold voltage



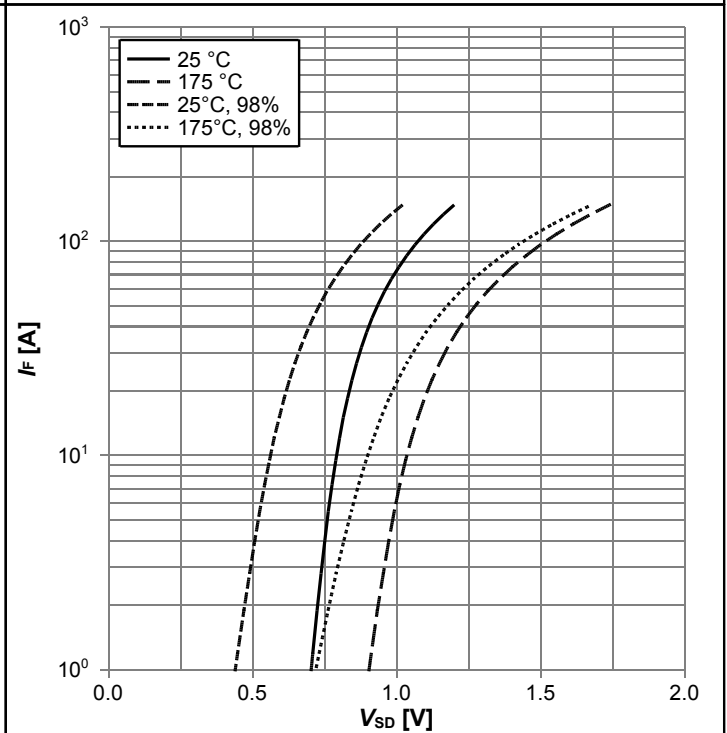
$V_{GS(th)}=f(T_j)$; $V_{GS}=V_{DS}$; parameter: I_D

Diagram 11: Typ. capacitances



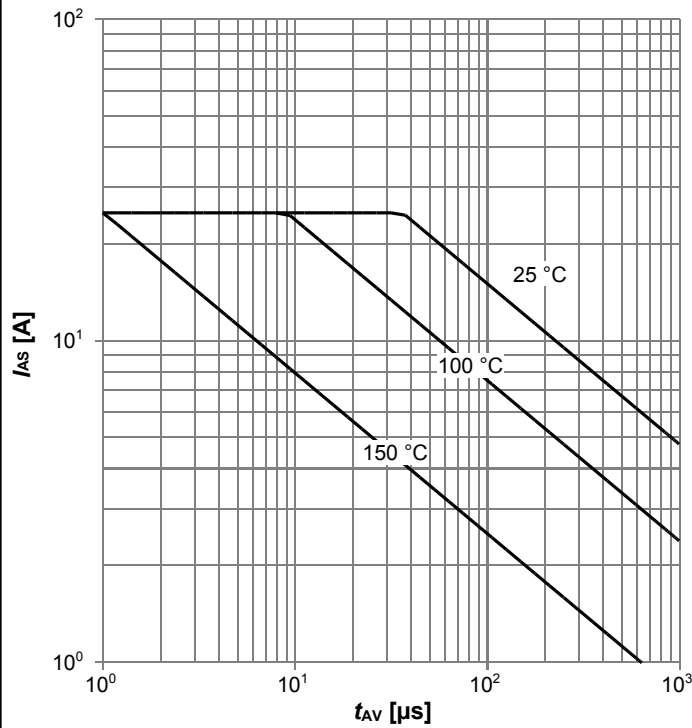
$C=f(V_{DS})$; $V_{GS}=0\text{ V}$; $f=1\text{ MHz}$

Diagram 12: Forward characteristics of reverse diode



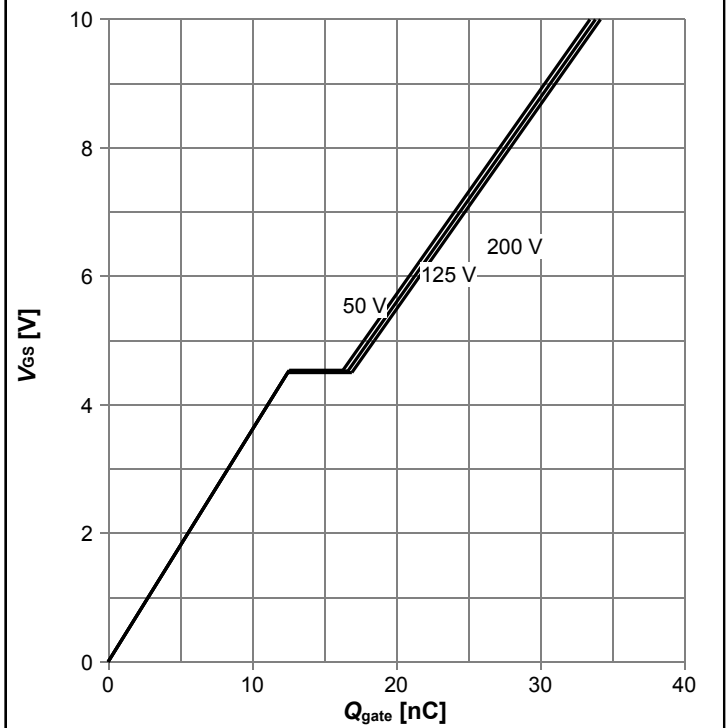
$I_F=f(V_{SD})$; parameter: T_j

Diagram 13: Avalanche characteristics



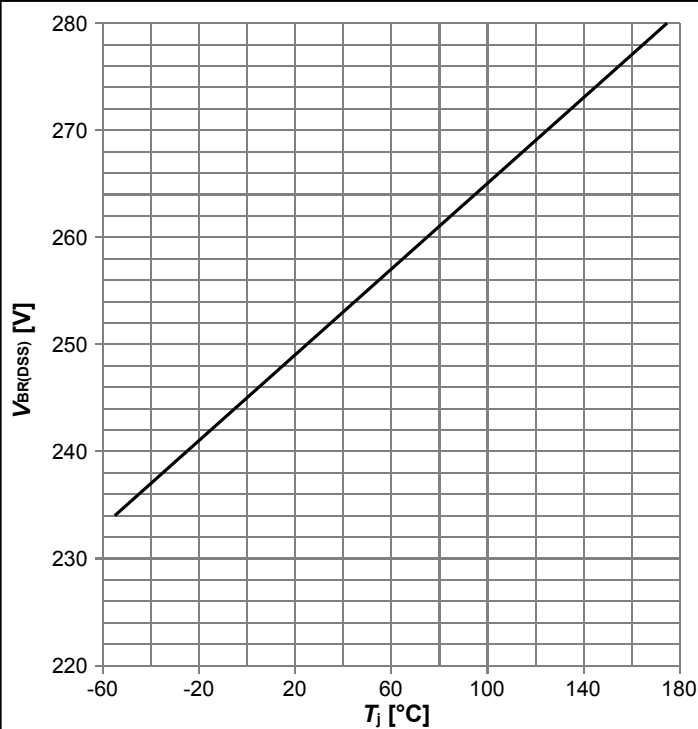
$I_{AS}=f(t_{AV}); R_{GS}=25 \Omega$; parameter: $T_{j(start)}$

Diagram 14: Typ. gate charge



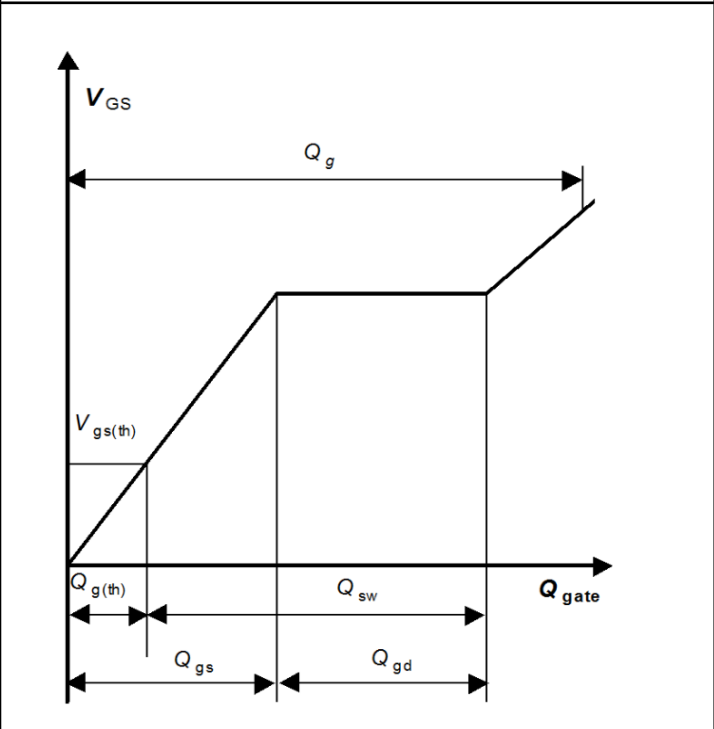
$V_{GS}=f(Q_{gate}); I_D=37 \text{ A pulsed}$; parameter: V_{DD}

Diagram 15: Drain-source breakdown voltage

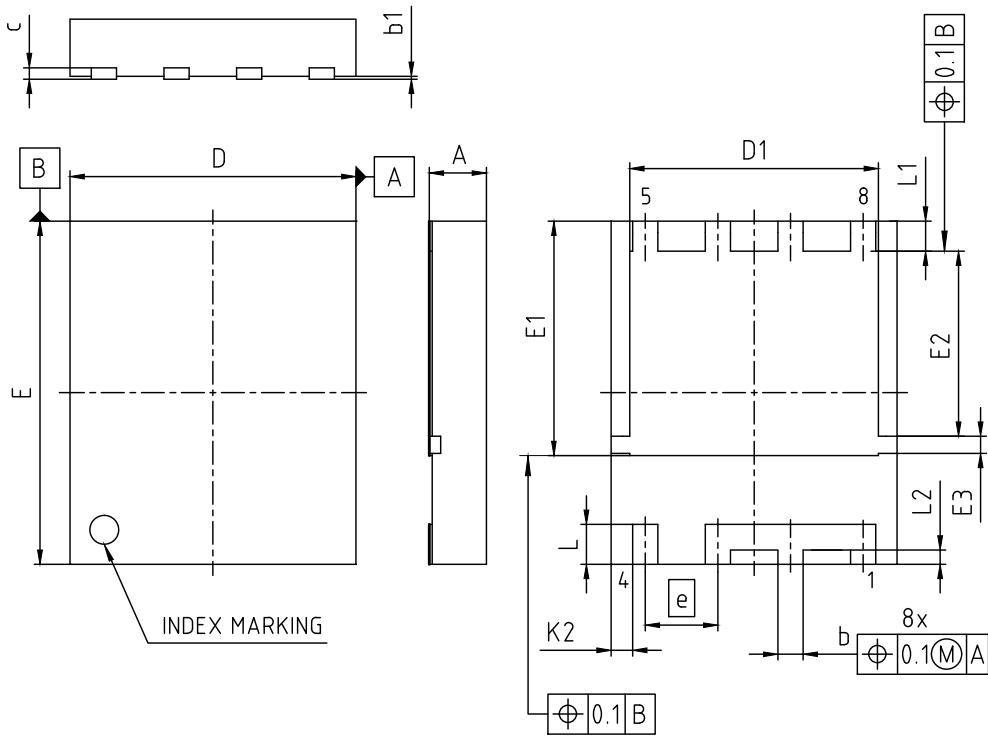


$V_{BR(DSS)}=f(T_j); I_D=1 \text{ mA}$

Diagram Gate charge waveforms



5 Package Outlines



DIMENSION	MILLIMETERS	
	MIN.	MAX.
A	-	1.10
b	0.34	0.54
b1	-	0.05
c	0.20	
D	4.90	5.10
D1	4.25	4.45
E	5.90	6.10
E1	4.00	4.20
E2	3.14	3.34
E3	0.20	0.40
e	1.27	
K2	(0.37)	
L	0.60	0.80
L1	0.43	0.63
L2	(0.25)	

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Figure 1 Outline TSON-8-3, dimensions in mm/inches

Revision History

BSC430N25NSFD

Revision: 2018-05-14, Rev. 2.1

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.0	2018-03-14	Release of final version
2.1	2018-05-14	Insert Rg max

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